AMP J - 522 (Rev. MAR

The product described in this document has not been fully tested to ensure conformance to the requirements outlined below. Therefore, AMP (Japan), Ltd makes no representation or warranty, express or implied, that the product will comply with these requirements. Further, AMP (Japan), Ltd. may change these requirements based on the results of additional testing and evaluation. Contact AMP Engineering for further details.

In case when "product specification" is referred to in this document, it should be read as "design objectives" for all times as applicable.

108-5409

0.8 mm Pitch Board To Board Connector

1. Scope:

### 1.1 Contents

SECUIIITY CLASSIFICATION: This specification covers the requirements for product performance, test methods and quality assurance provisions of 0.8 mm Pitch Board To Board Connector.

The applicable product descriptions and part number are as shown in Fig. 1:

Product Part No.	On Taping Part No.	Description
□-179207-□	□-179208-□	Plug Assembly Mating Height 5 mm without Positioner Boss
□-179209-□	□-179210-□	Cap Assembly V-type with Positioner Boss

Fig. 1

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### 2. Applicable Documents:

The following documents form a part of this specification to the extent specified herein. In the event of conflict between the requirements of this specification and the product drawing, the product drawing shall take precedence. In the event of conflict between the requirements of this specification and the referenced documents, this specification shall take precedence.

2.1 Military Standard and Specifications:

MIL-STD-202 Test Methods for Electronic and Electrical Component Parts

2.2 Commercial Standard and Specifications:

EIAJ (Electronic Industries Association of Japan) RCX-0102/101, 102 Test Method of Soldering of Surface Mounting Devices

- 3. Requirements:
- 3.1 Design and Construction:

Product shall be of the design, construction and physical dimensions specified in the applicable product drawing.

- 3.2 Materials:
  - A. Contact: Phosphor Bronze, Over all Nickel (Thickness:1.3-2.3µm)

    Dura-Gold Plated (Thickness:0.64µm minimum)

    Gold Plated (Thickness:0.05-0.127µm)
  - B. Housing: PCT (High heat-resisted polyester)
- 3.3 Ratings:

A. Voltage Rating:

50 V AC

B. Current Rating:

0.5 A

C. Temperature Rating:

-30°C to +105°C

3.4 Performance and Test Descriptions:

The product shall be designed to meet the electrical, mechanical and environmental performance requirements specified in Fig. 2. All tests shall be performed in the room temperature unless otherwise specified.

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3.5	Test Requirements and Procedures Summary:

Para.	Test Items	Requirements	Procedures
3.5.1	Confirmation of Product	Product shall be conforming to the requirements of applicable product drawing.	Visually, dimensionally and functionally inspected per applicable inspection plan.
		Electrical Requirements	
3.5.2	Termination Resistance (Low Level)	(Standard Type) V-Type: 25 mΩ max. (Initial) 50 mΩ max. (Final)	Subject mated contacts assembled in housing to closed circuit current of 10 mA max. at open circuit voltage of 20 mV max.  Fig. 5.
3.5.3	Insulation Resistance	500 MΩ min. (Initial) 100 MΩ min. (Final)	Measure by applying test potential between the adjacent contacts, and between the contacts and ground in the mated connector.  MIL-STD-202, Method 302, Condition A
3.5.4	Dielectric Strength	Connector must withstand test potential of 0.5 k V AC for 1 minute. Current leakage must be 0.5 mA max.	Measure by applying test potential between the adjacent contacts, and between the contacts and ground in the mated connectors.  MIL-STD-202, Method 301
3.5.5	Temperature Rising vs.	30 °C max. under loaded specified current.	Measure temperature rising by energized current.

Fig.2 (to be continued)

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Para.	Test Items	Requirements ,	Procedures
		Physical Requirements	
3.5.6	Vibration Sinusoidal Low Frequency	No electrical discontinuity greater than 1 microsecond (s) shall occur. Termination Resistance (Low level) (Final) V-Type: $50 \text{ m}\Omega$ max.	Subject mated connectors to 10-55-10 Hz traversed in 1 minute at 1.52 mm amplitude 2 hours each of 3 mutually perpendicular planes. applied. Fig. 6. MIL-STD-202, Method 201
3.5.7	Hammering Shocks	Termination Resistance (Low Level) (Final) V-Type: 50 mΩ max.	Subject mated connectors on PCB as shown in Fig. 6, under 10000 cycles of repeated hammering shocks of the condition as shown in Fig. 7, with the test current of 1 mA at 10 V DC applied to the circuit as shown in Fig. 8, During the test, the circuit shall be monitored for fluctuation of electrical resistance.
3.5.8	Physical Shock	No electrical discontinuity greater than 1 microsecond (s) shall occur. Termination Resistance (Low Level) (Final) V-Type: $50 \text{ m}\Omega$ max.	Subject mated connectors to 50 G's halfsine shock pluses of 11 millisecond duration, 3 shocks in each direction applied along the 3 mutually perpendicular planes totally 18 shocks MIL-STD-202, Method 213, Condition A
3.5.9	Connector Mating Force Unmating Force	Fig. 4	Measure the mating force and the unmating force when plug assembly and cap assembly are mated and unmated for 30 cycles at a rate of 20 mm a minute.
3.5.10	Contact Retention Force	0.1 kg min.	Apply axial load to contact
3.5.11	Durability (Repeated Mate / Unmating)	Termination Resistance (Low Level) (Final) V-Type: 50 mΩ max.	Mate and unmate connectors for 30 cycles

Fig.2 (to be continued)

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0.8 mm	Pitc	h Bo	ard T	o Board Connec	tor

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	Para.	Test Items	Requirements	· Procedures					
177-5409	3.5.12	Solderability	Appearance of the specimen shall be inspected after the test with the assistance of a magnifier capable of giving a magnification of 10×for an y damage such as pinholes, void or rough surface.	Provisional standards of EIA of JAPAN.  RCX-0102/101 (Test methods of soldering of surface mounting devises)  Para 2. 4. 2 (Reflow soldering method).					
elease NUMBER	3.5.13	Resistance to Soldering Heat	Appearance of the specimen shall be inspected after the test with the assistance of a magnifier capable of giving a magnification of 10×for damage such as cracks, chips or melting.	Provisional standards of EIA of JAPAN. RCX-0102/102 (Test methods of soldering of surface mounting devises) Para 3. 3. 4 (Hi-temp oven method)					
102			Environmental Requirements	5					
SECURITY CLASSIFICATION:	3.5.14	Thermal Shock	Termination Resistance (Low Level) (Final) V-type: 50 mΩ max.	Subject mated connectors to 5 cycles between -55°C and +85°C. MIL-STD-202, Method 107, Condition A					
	3.5.15	Humidity, Steady State	Insulation Resistance (Final) 100 M $\Omega$ min. Termination Resistance (Low Level) (Final) V-type: 50 m $\Omega$ max.	Subject mated connectors to steady state humidity at 40 °C and 90-95 % R.H. MIL-STD-202, Method 103, Condition B.					
<i>(</i>	3.5.16	Salt Spray	Termination Resistance (Low Level) (Final) V-type: 50 mΩ max.	Subject mated connectors to 5 % salt concentration for 48 hours; MIL-STD-202, Method 101, Condition B.					
	3.5.17	Heat Resistivity	Termination Resistance (Low Level) (Final) V-type: 50 mΩ max.	Subject mated connectors to heat resistivity at 85 ± 2 °C for 96 hours. per MIL-STD-202, Method 108, Condition A					

Fig. 2 (To be continued)

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0.8 mm Pitch Board To Board Connector						

Para.	Test Items	Réquirements .	Procedures
3.5.18	Cold Resistivity	Termination Resistance (Low Level) (Final) V-type: 50 mΩ max.	Subject mated connectors to cold resistivity at $-25\pm3$ °C for 48 hours.
3.5.19	Ammonia Gas Resistivity	Termination Resistance (Low Level) (Final) V-type: $50~m\Omega$ max.  Tested sample shall show no evidence of abnormalities in appearance	Subject mated connectors to the ammonia gas atmosphere, which is generated from 400 g of 28 % ammonia solution in the desiccator in the closed chamber for 40 minutes.  Temperature in the desiccator: room temperature.
3.5.20	Sulfurous Acid Gas Resistivity	Termination Resistance (Low Level) (Final) V-type: 50 mΩ max.  Tested sample shall show no evidence of abnormalities in appearance	Subject mated connectors to the sulfurous acid gas resistivity at $10\pm3$ ppm SO <sub>2</sub> concentration at 90 % R. H. min. for 96 hours.

Note: Tested products shall be conforming to the requirements of the visual inspection without physical damage, also meeting the requirements of the additional tests specified in the sequence tests specified in Fig. 3.

Fig. 2 (End)

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# 3.6 Product Qualification and Requalification Tests.

·				Test	Group	p (a)			
Test or Examination	1	2	3	4	5	6	7	8	9
	Test Sequence (b)								
Examination of Product	1,5	1	1,5	1,5	1,5	1	1	1,5	1
Termination Resistance, (Low Level)	2		2,4	2,4	2,4			2, 4	
Dielectric Withstanding Voltage	4		1						
Insulation Resistance	3								
Temperature Rise vs Current		2					<u> </u>		
Vibration			3						
Hammering Shocks				3					
Physical Shock			<u> </u>		3			ļ	
Mating Force, Unmating Force				<u>                                     </u>		2	<u> </u>		
Contact Retention				<u> </u>	<u> </u>		2		
Durability					ļ		<u> </u>	3	
Solderability							<u> </u>		2
Resistance to Soldering Heat					<u> </u>		<u> </u>		
Thermal Shock				<u> </u>					
Humidity, Steady State					ļ .			ļ	
Corrosion, Salt Spray									
Heat Resistivity				<u> </u>	<u> </u>	ļ			
Cold Resistivity				<u> </u>	ļ <u> </u>		<u> </u>	ļ	
Ammonia Gas Resistivity				<u> </u>	<u> </u>		ļ		
Sulfurous Asid Gas Resistivity								<u> </u>	

Fig. 3 (To be Continued)

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			Т	est Gr	oup (a	1)		
Test or Examination	10	11	12	13	14	15	16	17
·	Test Sequence (b)							
Examination of Product	1	1,5	1,6	1,5	1,5	1,5	1,5	1,5
Termination Resistance, (Low Level)		2,4	2,4	2, 4	2, 4	2,4	2, 4	2, 4
Dielectric Withstanding Voltage								
Insulation Resistance			5	<u> </u>				
Temperature Rise vs Current							ļ	
Vibration		<u></u>						
Hammering Shocks				<u> </u>				
Physical Shock					<u> </u>	ļ		
Mating Force, Unmating Force					ļ	<u> </u>		
Contact Retention							<u> </u>	
Durability								
Solderability				<u> </u>			<u> </u>	
Resistance to Soldering Heat	2							
Thermal Shock		3			<u> </u>		ļ	
Humidity, Steady State		<u> </u>	3			<u> </u>		
Corrosion, Salt Spray				3	<u> </u>			
Heat Resistivity		· .			3		<u> </u>	<u> </u>
Cold Resistivity	,					3		
Ammonia Gas Resistivity							3	ļ
Sulfurous Asid Gas Resistivity					<u> </u>			3

- (a) See Para 4.1.A.
- (b) Numbers indicate sequence in which tests are performed.
- (c) Discontinuities shall not take place in this test group, during tests.

Fig. 3 (End)

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## QUALITY ASSURANCE FROVISIONS

#### 4.1 Qualification Testing

#### Sample Selection Α.

Connector housing and contacts shall be prepared in accordance with applicable Instruction Sheets. They shall be selected at random from current production, Test group 1 shall consist of

Connectorr Mating Force / Unmatig Force

kg

No. of Pos.	Mating Force (max.)	Unmating Force (min.)
48	6.0	1.0

Fig. 4

Vertical Type

Fig. 5 Method of Termination Resistance Measuring

Connector

- Clamping Fixture

Vertical Type

Fig. 6 Method of Connector Mounting for Vibration And Hammering shock

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NAME 0.8 mm	Pite	h Bo	ard I	To Board Connec	tor

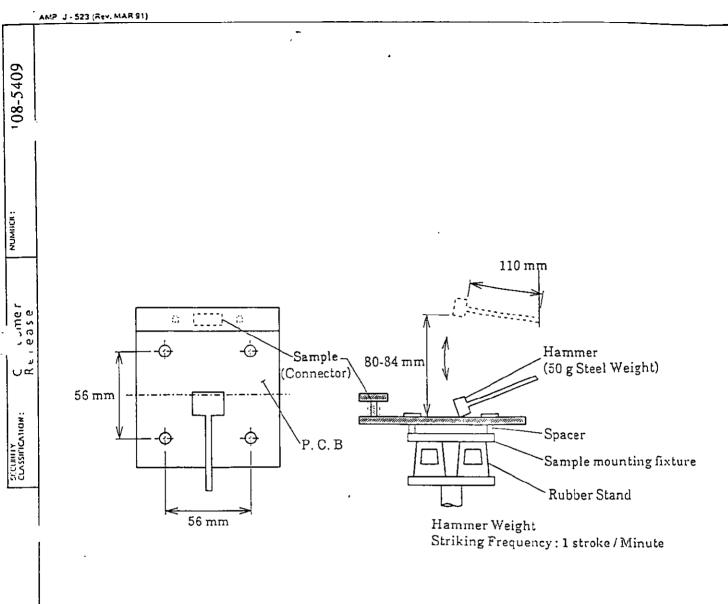


Fig. 7 Method of Hammering Shock Test

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NAME 0.8 mm	Pitc	h Bo	ard T	o Board Connect	or

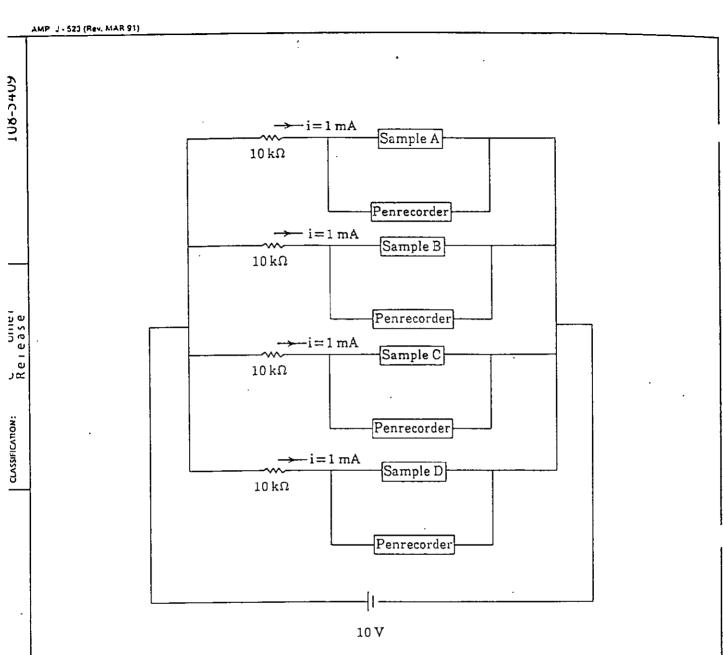


Fig. 8 Circuit of Monitoring Resistance

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